

# RT/duroid® 5880LZ

## Quick Reference Processing Guide

<b>Material Description:</b>	Copper-clad filled PTFE composite
<b>Storage:</b>	Ambient
<b>INNER LAYER PREPARATION</b>	
<b>Tooling:</b>	Compatible with most round and slotted hole systems.
<b>Surface Preparation for Photoresist Applications:</b>	Chemical preparation.
<b>Photoresist Applications:</b>	Standard film and liquid resists and procedures.
<b>DES Processing:</b>	Standard processing. Thin cores may require leaders.
<b>Oxide Treatment:</b>	Use procedures associated with oxide or oxide alternative of choice.
<b>BONDING</b>	
<b>Final Preparation:</b>	125°C to 150°C pre-bake required.
<b>Multilayer Adhesive System:</b>	Compatible with most thermoplastic and thermoset films.
<b>Multilayer Bond Cycle:</b>	Use bond parameters associated with adhesive system.
<b>PTH PROCESSING</b>	
<b>Drilling:</b>	Rigid and supportive entry/exit materials such as press phenolic. Use new drills. Controlled infeds, speeds, and retract rates. 12" rule for hole.
<b>Deburring:</b>	Mechanical debur/scrub not recommended. Very light applied pressure if debur is required.
<b>Hole Preparation:</b>	Pressurized water or air purge of holes is okay. Sodium or plasma treatments required prior to metal deposition. Bake required after sodium treatment.
<b>Metallization:</b>	Electroless copper (low or regular dep rates preferred over heavy dep processes) or direct deposit processes. Flash plate recommended prior to outer-layer imaging.
<b>OUTER LAYER IMAGING AND FINISHING</b>	
<b>Standard image, plate, etch and strip procedures apply.</b>	
<b>Final Surfaces:</b>	Compatible with most final metals surfaces and OSP's. Preserve post-etch surface and bake cores prior to application of LPI.
<b>Final Circuitization:</b>	Rout and punch as required. Material support and sharp edges on cutting tools required through mechanical processes.

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Revised 1301 051817 Publication #92-438